

TE Internal #: 6364666-2

Board-to-Board Card Edge Power Connector, 50 Position, 2.54 mm

[.1 in] Centerline, Power & Signal, 50 Power Positions, 0 Signal

Positions

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Connectors > PCB Connectors > Card Edge Connectors > Card Edge Power Connectors



Connector System: Board-to-Board

Number of Positions: 50

Centerline (Pitch): 2.54 mm [.1 in]

Contact Current Rating (Max): 4.26 A

Circuit Application: Power & Signal

### **Features**

### **Industry Standards**

UL Flammability Rating	UL 94V-0
Body Features	
Primary Product Color	Black
Mechanical Attachment	
Connector Mounting Type	Board Mount
Mating Retention Type	Latch
PCB Mount Retention	With
Mating Retention	With
PCB Mount Retention Type	Action/Compliant Tail
Mating Alignment Type	Keyed
Mating Alignment	With
PCB Mount Alignment	Without
Packaging Features	
Packaging Quantity	6



Other         Position Locations Omitted       44         EU RoHS Compliance       Compliant         EU ELY Compliance       Compliant         Termination Features         Termination Post & Tail Length       3.18 mm[,125 in]         Through Hole - Solder         Dimensions         Card Slot Depth       7.63 mm[,309 in]         Row-to-Row Spacing       4.85 mm[,191 in]         Connector Height       15.63 mm[,75 in]         Power Contact Centerline       2.54 mm[,1 in]         Contact Features         Contact Underplating Material         PCB Contact Termination Area Plating Material Thickness       .76 μm[30 μin]         PCB Contact Termination Area Plating Material Thickness       .254 μm[100 μin]         Contact Base Material       Phosphor Bronze         PCB Contact Termination Area Plating Material       Tin         Contact Termination Area Plating Material       Tin         Contact Termination Area Plating Material       Tin         Contact Termination Area Plating Material       Gold         Housing Area Plating Material       Gold <td colspan<="" th=""><th>Packaging Method</th><th>Box</th></td>	<th>Packaging Method</th> <th>Box</th>	Packaging Method	Box
EU RoHS Compliance Compliant  EU ELV Compliance Compliant  Termination Features  Termination Post & Tail Length 3.18 mml, 125 inj  Termination Method to PCB Through Hole - Solder  Dimensions  Card Slot Depth 7.63 mml, 309 inj  Row-to-Row Spacing 4.85 mml, 191 inj  Connector Height 15.63 mml, 75 inj  Power Contact Centerline 2.54 mml, 1 inj  Contact Features  Contact Underplating Material Nickel  PCB Contact Termination Area Plating Material Finish Matte  Contact Mating Area Plating Material Thickness 7.6 µml 30 µinj  PCB Contact Termination Area Plating Material Thickness 2.54 µml 100 µinj  Contact Base Material Phosphor Bronze  PCB Contact Termination Area Plating Material Thickness 2.54 µml 20 µinj  Contact Type Socket  Contact Type Socket  Contact Type Socket  Contact Mating Area Plating Material Gold  Housing Features  Housing Material Polyester GF  Configuration Features  Keying & Polyarzed Position I ocations 11, 12	Other		
EU ELV Compliance  Termination Features  Termination Post & Tail Length  Termination Method to PCB  Through Hole - Solder  Dimensions  Card Slot Depth  Row to Row Spacing  Connector Height  Power Contact Centerline  Contact Features  Contact Underplating Material  PCB Contact Termination Area Plating Material Thickness  PCB Contact Rase Material  PCB Contact Rase Material  PCB Contact Termination Area Plating Material Thickness  PCB Contact Termination Area Plating Material Thickness  Contact Rase Material  PCB Contact Rase Material  PCB Contact Termination Area Plating Material Thickness  Contact Rase Material  PCB Contact Termination Area Plating Material Thickness  Contact Rase Material  PCB Contact Termination Area Plating Material  PCB Contact Type  Socket  Contact Type  Contact Type  Contact Mating Area Plating Material  Housing Features  Housing Material  Polyester GF  Centerline (Pitch)  Configuration Features  Keying & Polarized Position Locations  11, 12	Position Locations Omitted	44	
Termination Features  Termination Post & Tail Length  Termination Method to PCB  Through Hole - Solder  Dimensions  Card Slot Depth  Row-to-Row Spacing  Connector Height  Power Contact Centerline  Contact Underplating Material  PCB Contact Termination Area Plating Material Finish  Contact Mating Area Plating Material Thickness  Contact Termination Area Plating Material Thickness  Contact Base Material  PCB Contact Termination Area Plating Material Thickness  Contact Base Material  PCB Contact Termination Area Plating Material Thickness  Contact Base Material  PCB Contact Termination Area Plating Material Thickness  Contact Mating Area Plating Material Thickness  Contact Termination Area Plating Material Thickness  Contact Termination Area Plating Material Thickness  Contact Termination Area Plating Material  Phosphor Bronze  PCB Contact Termination Area Plating Material  Tin  Contact Type  Socket  Contact Current Rating (Max)  4.26 A  Contact Mating Area Plating Material  Housing Features  Housing Material  Polyester GF  Centerline (Pitch)  Configuration Features  Keying & Polarized Position Locations  11, 12	EU RoHS Compliance	Compliant	
Termination Post & Tail Length Termination Method to PCB Through Hole Solder  Dimensions  Card Slot Depth 7, 63 mm[,309 in] Row-to-Row Spacing 4.85 mm[,191 in] Connector Height 15,63 mm[,75 in] Power Contact Centerline 2,54 mm[,11 in]  Contact Features  Contact Underplating Material Nickel PCB Contact Termination Area Plating Material Finish Matte Contact Mating Area Plating Material Thickness 7,6 µm[30 µin] PCB Contact Termination Area Plating Material Thickness 2.51 µm[100 µin] Contact Base Material Phosphor Bronze PCB Contact Termination Area Plating Material Thickness 0.50 µm[30 µin]  Contact Base Material Phosphor Bronze PCB Contact Termination Area Plating Material Tin Contact Type Socket Contact Current Rating (Max) 4.26 A Contact Mating Area Plating Material Gold  Housing Features  Housing Material Polyester GF Centerline (Pitch) 2.54 mm[,1 in]  Configuration Features  Keying & Polarized Position Locations 11, 12	EU ELV Compliance	Compliant	
Termination Method to PCB  Dimensions  Card Slot Depth 7.63 mm[.309 in] Row to Row Spacing 4.85 mm[.191 in]  Connector Height 15.63 mm[.75 in] Power Contact Centerline 2.54 mm[.1 in]  Contact Features  Contact Underplating Material Nickel PCB Contact Termination Area Plating Material Finish Matte  Contact Mating Area Plating Material Thickness 7.6 µm[30 µin]  PCB Contact Termination Area Plating Material Thickness 2.54 µm[100 µin]  Contact Base Material Phosphor Bronze  PCB Contact Termination Area Plating Material Thickness 2.56 µm[100 µin]  Contact Dase Material Phosphor Bronze  PCB Contact Termination Area Plating Material Thickness 3.00 cket  Contact Type Socket  Contact Current Rating (Max) 4.26 A  Contact Mating Area Plating Material Gold  Housing Features  Housing Material Polyester GF  Centerline (Pitch) 2.54 mm[.1 in]  Configuration Features  Keying & Polarized Position Locations 11, 12	Termination Features		
Dimensions  Card Slot Depth 7.63 mm[,309 in]  Row-to-Row Spacing 4.85 mm[,191 in]  Connector Height 15.63 mm[,75 in]  Power Contact Centerline 2.54 mm[,1 in]  Contact Features  Contact Underplating Material Nickel  PCB Contact Termination Area Plating Material Finish Matte  Contact Mating Area Plating Material Thickness 7.6 µm[30 µin]  PCB Contact Termination Area Plating Material Thickness 2.54 µm[100 µin]  Contact Base Material Phosphor Bronze  PCB Contact Termination Area Plating Material Thickness 5.0cket  Contact Type Socket  Contact Type Socket  Contact Current Rating (Max) 4.26 A  Contact Mating Area Plating Material Gold  Housing Features  Housing Material Polyester GF  Centerline (Pitch) 2.54 mm[,1 in]  Configuration Features  Keying & Polarized Position Locations 11, 12	Termination Post & Tail Length	3.18 mm[.125 in]	
Card Slot Depth 7.63 mm[.309 in]  Row-to-Row Spacing 4.85 mm[.191 in]  Connector Height 15.63 mm[.75 in]  Power Contact Centerline 2.54 mm[.1 in]  Contact Features  Contact Underplating Material Nickel  PCB Contact Termination Area Plating Material Finish Matte  Contact Mating Area Plating Material Thickness .76 µm[30 µin]  PCB Contact Termination Area Plating Material Thickness 2.54 µm[100 µin]  Contact Base Material Phosphor Bronze  PCB Contact Termination Area Plating Material Thickness .75 µm[30 µin]  PCB Contact Termination Area Plating Material Thickness .76 µm[30 µin]  Contact Base Material Phosphor Bronze  PCB Contact Termination Area Plating Material Tin Gold  Contact Type Socket  Contact Current Rating (Max) 4.26 A  Contact Mating Area Plating Material Gold  Housing Features  Housing Material Polyester GF  Centerline (Pitch) 2.54 mm[.1 in]  Configuration Features  Keying & Polarized Position Locations 11, 12	Termination Method to PCB	Through Hole - Solder	
Row to Row Spacing 4.85 mm[.191 in]  Connector Height 15.63 mm[.75 in]  Power Contact Centerline 2.54 mm[.1 in]  Contact Features  Contact Underplating Material Nickel  PCB Contact Termination Area Plating Material Finish Matte  Contact Mating Area Plating Material Thickness .76 µm[30 µin]  PCB Contact Termination Area Plating Material Thickness 2.54 µm[100 µin]  Contact Base Material Phosphor Bronze  PCB Contact Termination Area Plating Material Trin  Contact Type Socket  Contact Current Rating (Max) 4.26 A  Contact Mating Area Plating Material Gold  Housing Features  Housing Material Polyester GF  Centerline (Pitch) 2.54 mm[.1 in]  Configuration Features  Keying & Polarized Position Locations 11, 12	Dimensions		
Connector Height Power Contact Centerline 2.54 mm[.1 in]  Contact Features  Contact Underplating Material PCB Contact Termination Area Plating Material Finish Matte  Contact Mating Area Plating Material Thickness .76 µm[30 µin] PCB Contact Termination Area Plating Material Thickness 2.54 µm[100 µin]  Contact Base Material Phosphor Bronze PCB Contact Termination Area Plating Material Tin  Contact Type Socket  Contact Type Socket  Contact Current Rating (Max) 4.26 A  Contact Mating Area Plating Material Housing Features  Housing Material Polyester GF Centerline (Pitch) 2.54 mm[.1 in]  Configuration Features  Keying & Polarized Position Locations 11, 12	Card Slot Depth	7.63 mm[.309 in]	
Power Contact Centerline 2.54 mm[.1 in]  Contact Features  Contact Underplating Material Nickel  PCB Contact Termination Area Plating Material Finish Matte  Contact Mating Area Plating Material Thickness .76 µm[30 µin]  PCB Contact Termination Area Plating Material Thickness 2.54 µm[100 µin]  Contact Base Material Phosphor Bronze  PCB Contact Termination Area Plating Material Tin  Contact Type Socket  Contact Current Rating (Max) 4.26 A  Contact Mating Area Plating Material Gold  Housing Features  Housing Material Polyester GF  Centerline (Pitch) 2.54 mm[.1 in]  Configuration Features  Keying & Polarized Position Locations 11, 12	Row-to-Row Spacing	4.85 mm[.191 in]	
Contact Features  Contact Underplating Material PCB Contact Termination Area Plating Material Finish Matte  Contact Mating Area Plating Material Thickness .76 µm[30 µin]  PCB Contact Termination Area Plating Material Thickness 2.54 µm[100 µin]  Contact Base Material Phosphor Bronze  PCB Contact Termination Area Plating Material Tin  Contact Type Socket  Contact Current Rating (Max) 4.26 A  Contact Mating Area Plating Material Gold  Housing Features  Housing Material Polyester GF  Centerline (Pitch) 2.54 mm[.1 in]  Configuration Features  Keying & Polarized Position Locations 11, 12	Connector Height	15.63 mm[.75 in]	
Contact Underplating Material  PCB Contact Termination Area Plating Material Finish  Contact Mating Area Plating Material Thickness  PCB Contact Termination Area Plating Material Thickness  2.54 µm[100 µin]  Contact Base Material  Phosphor Bronze  PCB Contact Termination Area Plating Material  Tin  Contact Type  Socket  Contact Current Rating (Max)  4.26 A  Contact Mating Area Plating Material  Housing Features  Housing Material  Polyester GF  Centerline (Pitch)  Configuration Features  Keying & Polarized Position Locations  11, 12	Power Contact Centerline	2.54 mm[.1 in]	
PCB Contact Termination Area Plating Material Finish  Contact Mating Area Plating Material Thickness  .76 µm[30 µin]  PCB Contact Termination Area Plating Material Thickness  2.54 µm[100 µin]  Contact Base Material  Phosphor Bronze  PCB Contact Termination Area Plating Material  Tin  Contact Type  Socket  Contact Current Rating (Max)  4.26 A  Contact Mating Area Plating Material  Gold  Housing Features  Housing Material  Polyester GF  Centerline (Pitch)  Configuration Features  Keying & Polarized Position Locations  11, 12	Contact Features		
Contact Mating Area Plating Material Thickness .76 µm[30 µin]  PCB Contact Termination Area Plating Material Thickness 2.54 µm[100 µin]  Contact Base Material Phosphor Bronze  PCB Contact Termination Area Plating Material Tin  Contact Type Socket  Contact Current Rating (Max) 4.26 A  Contact Mating Area Plating Material Gold  Housing Features  Housing Material Polyester GF  Centerline (Pitch) 2.54 mm[.1 in]  Configuration Features  Keying & Polarized Position Locations 11, 12	Contact Underplating Material	Nickel	
PCB Contact Termination Area Plating Material Thickness  2.54 µm[100 µin]  Contact Base Material  Phosphor Bronze  PCB Contact Termination Area Plating Material  Tin  Contact Type  Socket  Contact Current Rating (Max)  4.26 A  Contact Mating Area Plating Material  Gold  Housing Features  Housing Material  Polyester GF  Centerline (Pitch)  2.54 mm[.1 in]  Configuration Features  Keying & Polarized Position Locations  11, 12	PCB Contact Termination Area Plating Material Finish	Matte	
Contact Base Material Phosphor Bronze  PCB Contact Termination Area Plating Material Tin  Contact Type Socket  Contact Current Rating (Max) 4.26 A  Contact Mating Area Plating Material Gold  Housing Features  Housing Material Polyester GF  Centerline (Pitch) 2.54 mm[.1 in]  Configuration Features  Keying & Polarized Position Locations 11, 12	Contact Mating Area Plating Material Thickness	.76 μm[30 μin]	
PCB Contact Termination Area Plating Material  Contact Type  Socket  Contact Current Rating (Max)  4.26 A  Contact Mating Area Plating Material  Gold  Housing Features  Housing Material  Polyester GF  Centerline (Pitch)  2.54 mm[.1 in]  Configuration Features  Keying & Polarized Position Locations  11, 12	PCB Contact Termination Area Plating Material Thickness	2.54 μm[100 μin]	
Contact Type Socket  Contact Current Rating (Max) 4.26 A  Contact Mating Area Plating Material Gold  Housing Features  Housing Material Polyester GF  Centerline (Pitch) 2.54 mm[.1 in]  Configuration Features  Keying & Polarized Position Locations 11, 12	Contact Base Material	Phosphor Bronze	
Contact Current Rating (Max)  Contact Mating Area Plating Material  Housing Features  Housing Material  Polyester GF  Centerline (Pitch)  Configuration Features  Keying & Polarized Position Locations  4.26 A  Gold  4.26 A  Gold  11, 12	PCB Contact Termination Area Plating Material	Tin	
Contact Mating Area Plating Material  Housing Features  Housing Material  Polyester GF  Centerline (Pitch)  2.54 mm[.1 in]  Configuration Features  Keying & Polarized Position Locations  11, 12	Contact Type	Socket	
Housing Features  Housing Material Polyester GF  Centerline (Pitch) 2.54 mm[.1 in]  Configuration Features  Keying & Polarized Position Locations 11, 12	Contact Current Rating (Max)	4.26 A	
Housing Material  Centerline (Pitch)  Configuration Features  Keying & Polarized Position Locations  Polyester GF  2.54 mm[.1 in]  11, 12	Contact Mating Area Plating Material	Gold	
Centerline (Pitch)  2.54 mm[.1 in]  Configuration Features  Keying & Polarized Position Locations  11, 12	Housing Features		
Configuration Features  Keying & Polarized Position Locations  11, 12	Housing Material	Polyester GF	
Keying & Polarized Position Locations 11, 12	Centerline (Pitch)	2.54 mm[.1 in]	
	Configuration Features		
PCB Mount Orientation Vertical	Keying & Polarized Position Locations	11, 12	
	PCB Mount Orientation	Vertical	
Number of Positions 50	Number of Positions	50	
Number of Power Positions 50	Number of Power Positions	50	
Number of Signal Positions 0	Number of Signal Positions	0	



Number of Dual Positions	25
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Product Type Features	
Connector & Contact Terminates To	Printed Circuit Board
Connector Mates With	Printed Circuit Board
Connector & Housing Type	Receptacle
Connector System	Board-to-Board
Electrical Characteristics	
Operating Voltage	400 V
Usage Conditions	
Operating Temperature Range	-55 – 90 °C[-67 – 194 °F]
Operation/Application	

Power & Signal

## **Product Compliance**

Circuit Application

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2024 (241) Does not contain REACH SVHC
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Wave solder capable to 265°C

#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-onreach



# Compatible Parts



# Customers Also Bought

















### **Documents**

**Product Drawings** 

**CONN SEC II 25 POS W/ LATCH** 

English

### **CAD Files**

**Customer View Model** 

ENG\_CVM\_6364666-2\_D.3d\_igs.zip

English

**Customer View Model** 

ENG\_CVM\_6364666-2\_D.3d\_stp.zip

English

**Customer View Model** 

ENG\_CVM\_6364666-2\_D.2d\_dxf.zip

English

3D PDF

Board-to-Board Card Edge Power Connector, 50 Position, 2.54 mm [.1 in] Centerline, Power & Signal, 50 Power Positions, 0 Signal Positions



English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

**Product Specifications** 

**Application Specification** 

English